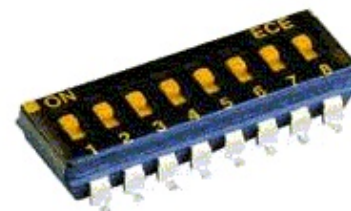


**EAD SERIES
AUTO INSERTING SMT TYPE**



FEATURES

- Same size with IC, can be assembled by any automatic IC inserter.
- Molded 0.3" integrated circuit packing outline allowing automatic insertion.
- Smaller size makes better heat convection during PC board reflow wave soldering.
- Top tape sealed to withstand wave soldering, board washing.
- All plastics are UL 94V-0 grade fire retardant.
- Gold plated contact to ensure low contact resistance and Tin plated terminals to prevent contamination during soldering.

SPECIFICATIONS

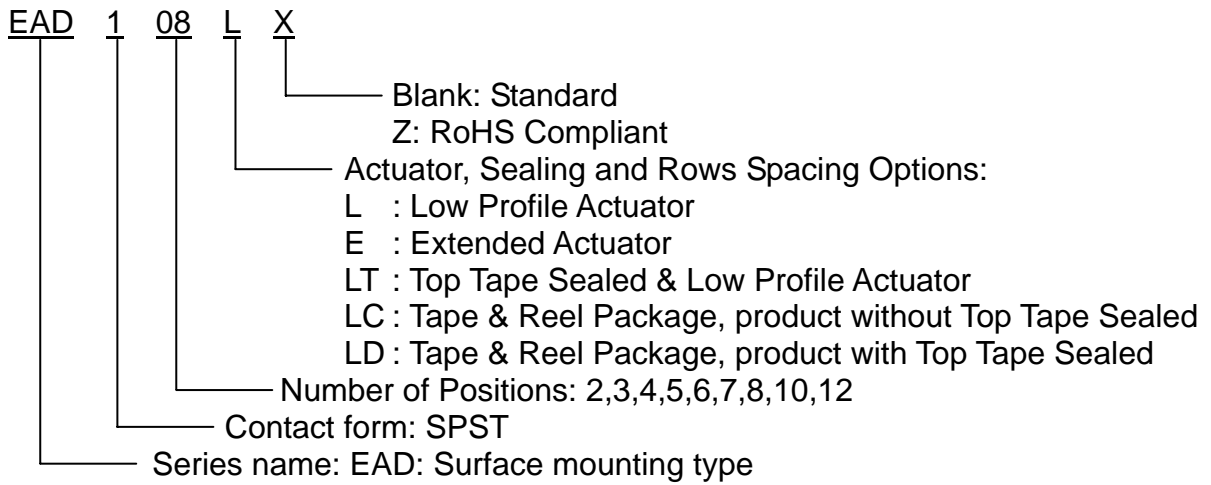
1.ELECTRICAL

● Contact rating	switching	25mA, 24VDC
	non-switching	100mA
● Contact resistance	initial	50mΩ Max.
	after life test	100mΩ Max.
● Insulation resistance	1000MΩ Min. at 100VDC	
● Dielectric strength	500VDC Min. for 60 seconds	
● Capacitance between adjacent switches	5pF Max.	

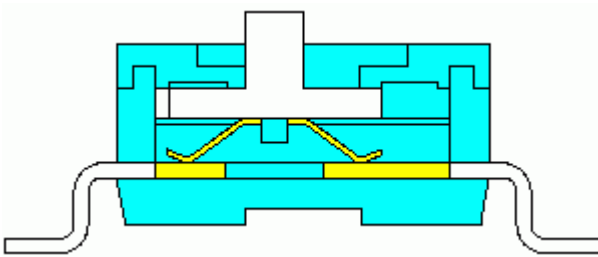
2.MECHANICAL and ENVIRONMENTAL

● Temperature rating	operating	-25°C to +70°C
	storage	-40°C to +85°C
● Operation force	800g Max.	
● Mechanical life	2000 operations	
● Humidity	95% RH, 40°C for 96 Hrs.	
● Vibration	Per MIL-STD-202F, method 204D.	
● Reflow soldering heat for SMT type (reference only)		

■ PART NUMBERING SYSTEM



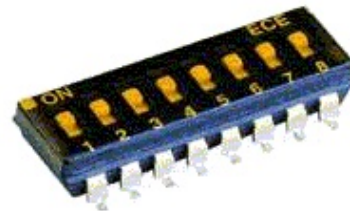
■ CONSTRUCTION



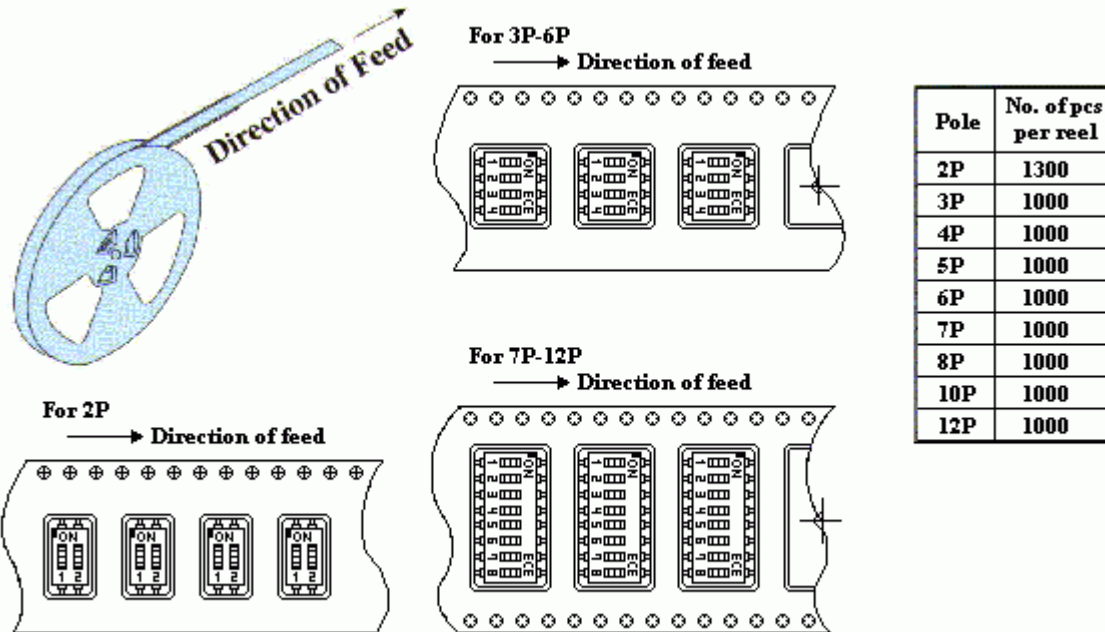
■ OPTIONS

1. Special marking and case color available
2. Extended Actuator

3. Top Tape Sealed



4. Tape & Reel Packaging (per EIA STANDARD)



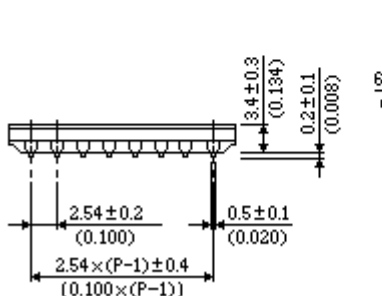
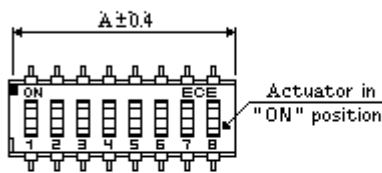
DIMENSIONS AND CIRCUITRY

DIMENSION A

Positions	2	3	4	5	6	7	8	10	12
A	6.88 (0.271)	9.42 (0.371)	11.96 (0.471)	14.50 (0.571)	17.04 (0.671)	19.58 (0.771)	22.12 (0.871)	27.20 (1.071)	32.28 (1.271)

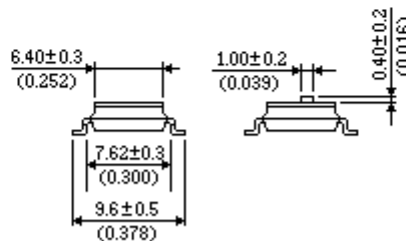
Unit: mm(inch)

CIRCUIT DIAGRAM



(L) TYPE

(R) TYPE



P.C.B. LAYOUT (TOP VIEW)

